## **TE0726 TRM**

### Tabile of Proprinciples document.

```
Overview

1.1 Key Features
The Trenz Electrosic, 1-2 Burck Diagram
The Trenz Electrosic, 1-2 burch San industrial/extended grade module based on AMD Zynq 7 Series. It is
Raspberry Pi Journ factor compatible state
Refer to http://results.interfaces.and.Pins.
Refer to http://results.interfaces.and.Pins.
2.1 Connectors
documentation. 2.1 Connectors
           • 3 On-board Peripherals
Key Feat 1505m Controller CPLD

    3.3 USB-PHY

    SoC/FPGA/Modulernet Hub

                                 ○ ③. Padkage:
                                                                                                      CLG225
          • 4 Configuration Properties

• 3.6 [27] Expander Z-7007S, Z-7010, 1)

• 3.7 [27] Interrupts

• 3.6 [27] Expander Z-7007S, Z-7010, 1)

• 4 Configuration Commercial / Extended / Industrial 1)

• 4 Configuration Control Signature

• 5 FAMILY REPORT FOR PAN 1)
                                o 5.5120 MByReaDDDR3L ECC RAM 1)
                                o 5.26 MByrenQSrt4dFRswell up Sequencing
          • 6 Technical SKBRIER ROM for FTDI
                                ○ 6.2 KBIPEEPROMITONETHOSINGS & USB HUB

    On Board Recommended Operating Conditions

    6.35 Pstrenice on information PRLD

    7 Currendy Offered Mathemasceiver

                8 Revision 110/11000 Ethernet Transceiver with USB hub
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                                ° 8.3x Micro USB (UART/JTAG)
           • 9 Disclaimetx USB 2.0
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                                ° 9.2 ₽B6Wneele of a preswitch
                                o 9.3 killithetinet #J48 bibbket
                                ் அ. 1 இராகு Author Gack 3.5mm with microphone (PWM audio only)
                                ○ 9.5 T PHDIMPICON NECROFES
                                ° 9.9 € CSIC2 Confrector (Camera Serial Interface)
                                o 9.7 R 58 Commed to P (Display Serial Interface)
           • 10 Tablecof 15050 Paint Header for I2C
                                      o 2x20 Pin Header with 26 GPIO, 1x I2C, 5 and 3.3 V
                                            3 additional Pinheaders for CPLD access, Reset and PUDC (SoC Boot IO State)
                                             changes

    Power

                                      o via Micro USB
                                      o via 5V Pin header

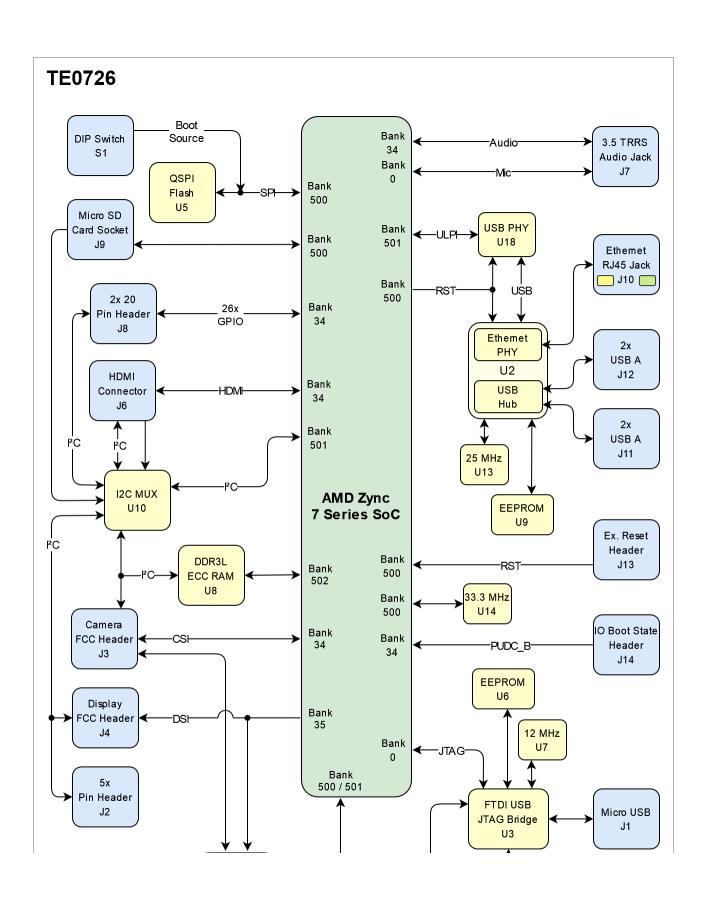
    Dimension

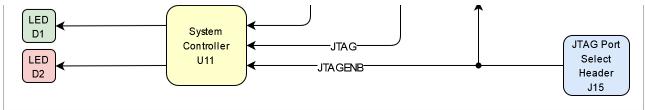
    56 mm x 85 mm, like Raspberry Pi

    Notes

                       1) Depends on assembly variant
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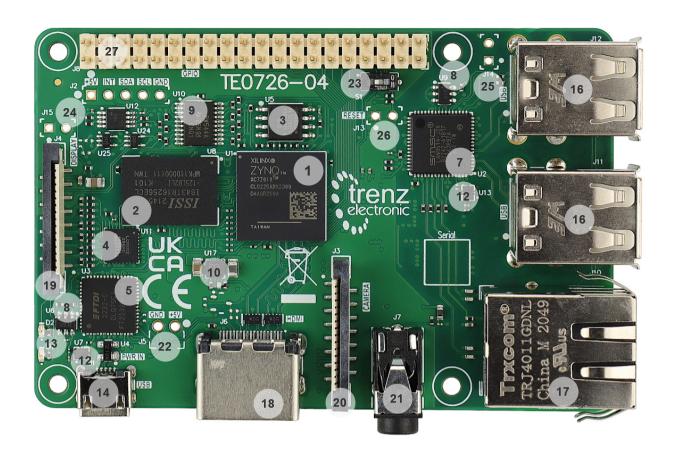
## **Block Diagram**

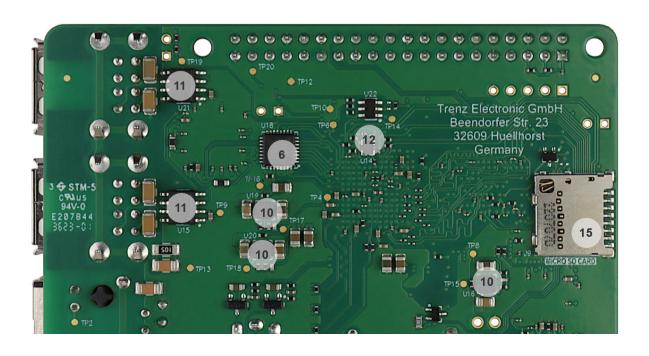




TE0726 block diagram

# **Main Components**







#### TE0726 main components

- 1. AMD 7 Series Zynq, U1
- 2. DDR3L ECC RAM, U8
- 3. SPI Flash, U5
- 4. System Controller CPLD, U11
- 5. FTDI USB to multipurpose JTAG/FIFO, U3
- 6. USB Transceiver, U18
- 7. Ethernet Transceiver LAN9514 with 4 port USB Hub, U2
- 8. EEPROM, U6, U9
- 9. I<sup>2</sup>C Multiplexer, U10
- **10.** Power Supply, U16, U17, U19, U20
- 11. USB power switch, U15, U21
- **12.** Oscillator, U14 , U13 , U7 **13.** LED, D1 , D2
- 14. Micro USB B receptacle, J1
- **15.** microSD card, J9 **16.** 2x USB A, J11 , J12
- 17. RJ-45 Ethernet connector, J10
- **18.** HDMI connector, J6
- 19. DSI LCD connector, J4
- 20. CSI camera connector, J3
- 21. 3.5mm RCA audio jack, J7
- 22. +5V Power Connector, J5
- 23. Boot DIP switch, S1
- 24. JTAG Port select header, J15
- 25. Boot IO State select header, J14
- 26. Externer reset header, J13
- 27. 2x20 pin header, J8

## **Initial Delivery State**

Storage device name	Content	Notes
Quad SPI Flash	not programmed	
EEPROM FTDI	preprogrammed	
EEPROM ETH	not programmed	
System Controller CPLD	preprogrammed	

Initial delivery state of programmable devices on the module

## Signals, Interfaces and Pins

### **Connectors**

Connector Type	Designator	Interface	IO CNT	Notes
2x 20 2.54 mm Pin Header	J8	GPIO (HR)	26	

2x 20 2.54 mm Pin Header	J8	I <sup>2</sup> C	2	Multiplexer U10
2x 2.54 mm Pin Header	J15	JTAG select	1	SoC or SC select
2x 2.54 mm Pin Header	J14	Boot IO State select	1	
2x 2.54 mm Pin Header	J13	External reset	1	
2x USB A stacked	J11, J12	USB 2.0	12	To USB PHY (ULPI)
5x 2.54 mm Pin Header	J2	I <sup>2</sup> C	2	Multiplexer U10, I <sup>2</sup> C shared with J4
5x 2.54 mm Pin Header	J2	Interrupt	1	Multiplexer U10
DIP switch	S1	Boot select	1	Shared with SPI
FCC	J4	MIPI DSI	6 (3 pairs)	
FCC	J4	I <sup>2</sup> C	2	Multiplexer U10
FCC	J3	I <sup>2</sup> C	2	Multiplexer U10
FCC	J3	MIPI CSI-2	8 (4 pairs)	
HDMI	J6	HDMI	8 (4 pairs)	
HDMI	J6	I <sup>2</sup> C	2	Multiplexer U10
HDMI	J6	Interrupt	1	Multiplexer U10
Micro-USB 2.0 B	J1	JTAG	2 (1 pair)	SoC or SC selectable
microSD Card	J9	Interrupt	1	Multiplexer U10
microSD Card	J9	SD	5	
RJ-45 Ethernet	J10	10/100 ETH	12	To USB PHY (ULPI)
TRRS 3.5 mm	J7	RCA Audio	2	
TRRS 3.5 mm	J7	RCA Mic	1	

**Board Connectors** 

# **Test Points**

Test Point	Signal	Notes
TP1	TDI	
TP2	3.3V	
TP3	TDO	
TP4	1.8V	
TP5	TCK	
TP6	1.0V	
TP7	TMS	
TP8	1.35V	
TP9	5V	
TP10	GND	

TP11	GND	
TP12	GND	
TP13	GND	
TP14	POR B	Zync SoC reset signal
TP15	PG_1.35V	Power good signal
TP16	PG_1.8V	Power good signal
TP17	PG_3.3V	Power good signal
TP18	PG_1.0V	Power good signal
TP19	PUDC	Zynq SoC IO State during boot process
TP20	SPI0_DQ3/M0	Boot source select signal

**Test Points Information** 

# On-board Peripherals

Chip/Interface	Designator	Connected To	Notes
DDR3L RAM	U8	<ul> <li>Zynq SoC DDR Interface PS Bank 502</li> </ul>	
System Controller CPLD	U11	<ul> <li>Zynq SoC MIO Bank 35</li> <li>MIDI DSI J4</li> <li>MIDI CSI J3</li> <li>FTDI U7</li> <li>LEDs</li> </ul>	
USB-PHY	U18	Zynq SoC MIO and Zynq SoC USB ULPI	
USB Ethernet Hub	J10	USB PHY USB A connectors J11 and J12 Power switch for USB A connectors U15, U21 ETH connector J10 EEPROM U9	
FTDI	U3	JTAG to System     Controller and Zynq     SoC     EEPROM U6	

I <sup>2</sup> C Expander	U10	<ul> <li>Zynq MIO (Bus master)</li> <li>DDR3L via Voltage Bridge U12 shared with MIDI CSI J3</li> <li>MIDI DSI J4 and Pin Header J2</li> <li>HDMI socket J6</li> <li>Pin header J8</li> </ul>	
I <sup>2</sup> C Interrupts	U10	<ul> <li>Zynq MIO (Bus master)</li> <li>microSD Card socket J9 inseration detection</li> <li>HDMI J6 inseration detection</li> <li>Pin header J2</li> </ul>	
Oscillator	U14	Zynq SoC - PS	33.3 MHz
Oscillator	U9	• USB PHY	25 MHz
Oscillator	U7	• FTDI	12 MHz

On board peripherals

# Configuration and System Control Signals

Connector	Signal Name	Direction <sup>1)</sup>	Description
S1	SPI0_DDQ3 / MO	IN	Boot source switch, SPI flash or SD Card
J13	EXTRST, POR_B, nRST	IN	Reset Zynq SoC
J14	PUDC	IN	State of Zynq SoC IO lines during boot
J15	JMODE , BDBUS7	IN	JTAG endpoint selction, System Controller or Zynq SoC

<sup>1)</sup> Direction:

- IN: Input from the point of view of this board.
   OUT: Output from the point of view of this board.

Controller signal.

# Power and Power-On Sequence

### **Power Rails**

Power Rail Name/ Schematic Name	Connector + Pin	Direction <sup>1)</sup>	Notes
USB_B_Vbus	J1	IN	Default power supply 5V
5V	J5.1	IN/OUT	2x Pin Header, intended for alternative powering
5V	J2.1 J8.2 , J8.4	OUT	5x Pin Header 2x 20 Pin Header
5V_HDMI	J6.18	OUT	HDMI, reverse current protection diode D11
V_BUS_A , V_BUS_B , V_BUS_C , V_BUS_D	J11.A1 , J11.B1 , J12.A1 , J12.B1	OUT	2x USB A socket
3.3V	J8.1 , J8.17 J3.15 J4.15 J9.4	OUT	2x 20 Pin Header FCC CSI FCC DSI microSD Card socket

### 1) Direction:

- IN: Input from the point of view of this board.
   OUT: Output from the point of view of this board.

Module power rails.

# **Recommended Power up Sequencing**

Sequence	Net namæecor	nmended Voltage	Ra <b>iPguel</b> -up/down	Description	Notes
1	USB_B_Vbus	5V (± 5 %)	-	Main Power supply via Micro- USB J1.	Main module power supply. 0.5 A minimum. Power consumption depends mainly on design and cooling solution. If more current is needed use J5 for external power supply.
2	3.3V	-	-	Module generated output voltage.	
3	-	-	-	External components which are connected to J8 should be powered up with 3.3V from module.	See link: https://docs.amd. com/v/u/en-US /ds187- XC7Z010- XC7Z020-Data- Sheet , page 8 "PL PowerOn/Off Power Supply Sequencing" for PL IO usage

**Baseboard Design Hints** 

## **Technical Specifications**

# **Absolute Maximum Ratings** \*)

Power Rail / Schematic Name	Description	Min	Мах	Unit
USB_B_Vbus	Determined through "USB 2.0 VBUS Max Limits"	4.75	5.5	V
5V	Determined through "USB 2.0 VBUS Max Limits"	4.75	5.5	V

#### Absolute maximum ratings

## **Recommended Operating Conditions**

This TRM is generic for all variants. Temperature range can be differ depending on the assembly version. Voltage range is mostly the same during variants (exceptions are possible, depending on custom request)

Operating temperature range depends also on customer design and cooling solution. Please contact us for options.

- Variants of modules are described here: Article Number Information
- Modules with commercial temperature grade are equipped with components that cover at least the range of 0°C to 75°C
- Modules with extended temperature grade are equipped with components that cover at least the range of 0°C to 85°C
- Modules with industrial temperature grade are equipped with components that cover at least the range of -40°C to 85°C
- The actual operating temperature range will depend on the FPGA / SoC design / usage and cooling and other variables.

Parameter	Min	Мах	Units	Reference Document
USB_B_Vbus	4.75	5.25	V	Schematic of this board. SCH-TE0726- 04-41C94-A.PDF page 3, table "Supported Voltage Ranges"
5V	4.75	5.25	V	Schematic of this board. SCH-TE0726- 04-41C94-A.PDF page 3, table "Supported Voltage Ranges"

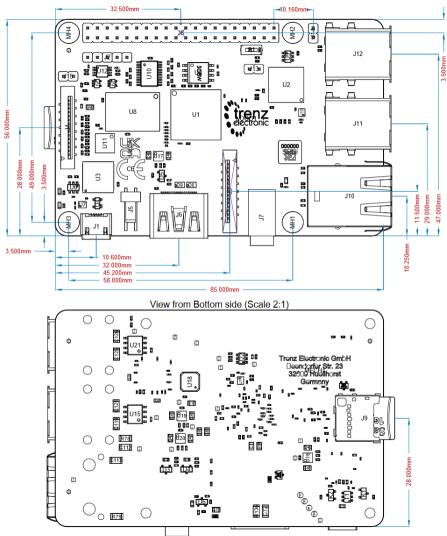
Recommended operating conditions.

## **Physical Dimensions**

• Module size: 85 mm x 56 mm. Please download the assembly diagram for exact numbers.

<sup>\*)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Condition. Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

PCB thickness: 1.57 mm ± 10 %.





1.558mm-

**Physical Dimension** 

# **Currently Offered Variants**

Trenz shop TE0726 overview page	
English page	German page
Trenz Electron	ic Shop Overview

**Revision History** 

# **Hardware Revision History**



#### Board hardware revision number.

Date	Revision	Changes	PCN Link	Documentation Link
2023-06-10	Revision 04	Changes  Page Numbers refer to the schematic for this revision	PCN-20230619 TE0726-03 to TE0726-04 Hardware Revision Change	Documentation Link TE0726-04

- EOL components U16, U17 , U19, U20 (EN5311QI)
- were replaced by MPM3834CGPA Added MIC bias power L12, C114 , R151 (Page 16) Added Legal
- notices (Page 1) Added power
- diagram (Page 4) Added S1 switch and R152 for "JTAG only mode" enable (Page 8)
- The signals were renamed:

  SPI-DQ0
  /M0 --->
  SPI-DQ0
  - /M3 SPI-DQ3
  - /M3 ---> SPI-DQ3 /M0
- ECC function has been added for U8 (Page 11)

  Added I2C level shifter U12 for
- function (Page 11) Added Buffers
- U24, U25 to match the level of signals (Page
- 6)
   Added Diode D7, resistors R155, R160
- EOL components L1, L2, L3, L4, L6, L7, L9, L10 BKP0603HS121-T replaced by MPZ0603S121HT
- 000 EOL components D8, D9 SP5001-04TTG replaced
- by EMI8042MUTAG
- Resistors R80-R82 replaced by 10 kOhm (was 1k43)
- Added Testpoints TP15 TP20
- The type of testpoints TP1 -TP14 was updated. Diameter changed from
- 0.8 mm to 1 mm CEC function is not supported. L11 was removed. C127, D5, R140, R42 are DNP
- Power-up sequencing was updated for new DC-DC supplies
- Capacitors C29, C32, C33 replaced by 470 nF (was 100 nF)

2021-01-21	03	Change DDR3 RAM (U8) from IM4G16D3FABG- 125I to IS43TR16256BL- 125KBLI Clock Revision Change (U7, U14) from SiT8008BI Clock Revision Change (U13) from SiT8008BI LEDs D1 and D2 changed to 19- 213/G6C-BM1N2 /DT and 19-213 /R6C-AL1M2VY /3T Set S/N to not fitted	PCN-20210121 TE0726-03 DDR3 Change and Product Update	TE0726-03
2019-04-08	03	VBUS Resistor R94 replaced by 10 kOhm (was 12k1)	-	TE0726-03
2016-05-06	03	Introduced new variants: DEFault with DDR3L DDR3L DDR3L DDR3L DDR3L S12 Mb TE0726- 03M with DDR3L S12 Mb TE0726- 03L with DDR3L TE0726- S1 with DDR3L S128 Mb, without usb's, eth_phy, RJ-45, CSI, DSI, HDMI and 3.5mm jack connectors Changed FTDI to 56 pins package Moved LED's into Raspberry Pi 3 layout Replaced POWER connector on right angle connector Corected conection PUDC pin Replace HDMI, DSI/CSI connector, USB stacked connectors, RJ-45, power connector)	-	TE0726-03

2016-01-26	02	CSI CLK line moved to MRCC pin, CSI lanes swap CSI camera GPIO moved to MIO GPIO RPI GPIO 14,15 moved from MIO to PL Added 47 µF capacitor for SD Card VCC (required by SD spec) Added 47 µF capacitor for RPI camera - prevent voltage drop at camera init Fixed MODE pin strapping LED change 0603 Added POWER connector 2 pin Change HDMI ESD to ESD+EMI Fixed HDMI HPD and backpower DSI find solution for LS mode Fixed XADC power caps Changed LPDRR2 to DDR3L	-	TE0726-02
-	01	<ul> <li>Inital board release</li> </ul>	-	-

Hardware Revision History

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.

# **Document Change History**

Date	Revision	Contributor	Description
Error renderi ng macro 'page- info'	Error renderi ng macro 'page- info'	Error renderi ng macro 'page- info'	Updated to new TRM style.     Updated to board REV04.
Ambiguo	Ambiguo	Ambiguo	
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2017-11-10	v.52	John Hartfiel	• rework J8 header
2017-11-10	v.51	Ali Naseri	Updated Power section     added Power-Distribution diagram
2017-05-30	v.40	Jan Kumann	Absolute maximum ratings     Layout redesign     Wiki link fixed     SoC model removed from BD
2017-05-24	v.1	Jan Kumann	Initial version
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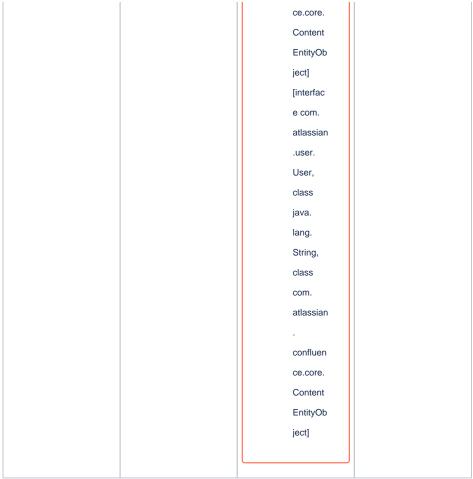
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Document change history.

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Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

#### Error rendering macro 'page-info'

Ambiguous method overloading for method jdk.

proxy241.\$Proxy3496#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user. ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.

ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]